



Material Content Data Sheet



Sales Product Name				SAK-TC237LP-32F200S AC		Issued		1. August 2018	
MA#				MA001677586					
Package				PG-LFBGA-292-6		Weight*		934.32 mg	
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	9.859	1.06	1.06	10553	10553	
wire	noble metal	palladium	7440-05-3	0.014	0.00		15		
	non noble metal	copper	7440-50-8	1.396	0.15	0.15	1494	1509	
encapsulation	organic material	carbon black	1333-86-4	0.731	0.08		783		
	plastics	epoxy resin	-	50.464	5.40		54012		
	inorganic material	silicondioxide	60676-86-0	314.485	33.65	39.13	336594	391389	
substrate	plastics	epoxy resin	-	6.479	0.69		6934		
	inorganic material	bariumsulfate	7727-43-7	9.942	1.06		10641		
	plastics	acrylic resin	-	11.506	1.23		12314		
	inorganic material	aluminiumhydroxide	21645-51-2	53.265	5.70		57010		
	plastics	epoxy bismaleimide triazine resin	-	61.156	6.55		65456		
	inorganic material	glass fibre	-	82.857	8.87		88682		
	non noble metal	copper	7440-50-8	196.577	21.04	45.14	210397	451434	
plating	noble metal	gold	7440-57-5	3.137	0.34		3357		
	non noble metal	nickel	7440-02-0	3.137	0.34	0.68	3357	6714	
solderball	noble metal	silver	7440-22-4	4.457	0.48		4771		
	non noble metal	tin	7440-31-5	122.898	13.15	13.63	131538	136309	
glue	plastics	epoxy resin	-	0.489	0.05		523		
	noble metal	silver	7440-22-4	1.466	0.16	0.21	1569	2092	
*deviation	< 10%			Sum in total:		100.00		1000000	

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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